

IRVINE SENSORS CORPORATION NEWS RELEASE

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FOR IMMEDIATE RELEASE

IRVINE SENSORS ANNOUNCES NEW LINE OF STACKED MEMORY PRODUCTS **First Ball Grid Array (BGA) product is stack of Double Data Rate parts**

COSTA MESA, CALIFORNIA – August 12, 2003 -- Irvine Sensors Corporation (Nasdaq: IRSN, Boston Stock Exchange: ISC) today announced the schedule for availability of the first of an expected new line of stacked computer memory packages using Ball Grid Array (BGA) attachment technology. BGA attachments use an array of solder balls for interconnects rather than rows of leads, thereby using much less area and saving valuable mounting space on circuit boards. Over the next several years, BGA attachment technology is anticipated to be the successor to the industry-standard Thin Small Outline Package (TSOP) packaging technology that has been used in the semiconductor industry for over a decade. In response to this transition, Irvine Sensors is introducing a family of stacked BGA parts that takes advantage of its patented technology to permit the stacked package to use no more board space than a single device.

Irvine Sensors' initial product offering is a package of two stacked Micron® 256 Mb SDRAM Double Data Rate (DDR) 333 MHz parts. This product is expected to be available for deliveries commencing in September. A comparable product consisting of stacked Samsung® DDR parts is planned for release in the subsequent quarter. The manufacturing processes utilized for both parts are



comparable and adaptable to stacking numerous other BGA packages. Irvine Sensors expects to exploit this adaptability to expand its line to meet customer product demands and has established a “quick turn” manufacturing process intended to permit rapid response to customer requirements. Potential customers are invited to submit requests for quotation on stacks of any commercially available BGA packages. For information about pricing, schedule or product configurations of BGA products, please direct inquiries to BGASStack@irvine-sensors.com.

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The newly announced BGA product line is in addition to Irvine Sensors' existing line of more than two dozen different stacked TSOP packages. For information regarding Irvine Sensors' stacked TSOP products, please direct inquires to TSOPStack@irvine-sensors.com.

Irvine Sensors Corporation, headquartered in Costa Mesa, California, is primarily engaged in the sale of stacked chip assemblies and research and development related to high density electronics, miniaturized sensors and cameras, optical interconnection technology, high speed routers, image processing and low-power analog and mixed-signal integrated circuits for diverse systems applications.

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Micron and Samsung are registered trademarks of Micron Technology, Inc. and Samsung Electronics Co. Ltd., respectively.

Safe Harbor Statement under the Private Securities Litigation Reform Act of 1995: This news release may contain forward-looking statements based on our current expectations, estimates and projections about our industry, management's beliefs, and certain assumptions made by us. Words such as "anticipates," "expects," "intends," "plans," "believes," "seeks," "estimates," "may," "will" and variations of these words or similar expressions are intended to identify forward-looking statements. These statements include, but are not limited to, our expectations regarding the market demand for our BGA parts and our ability to qualify, manufacture and respond to that demand. Such statements speak only as of the date hereof and are subject to change. We undertake no obligation to revise or update publicly any forward-looking statements for any reason. These statements are not guarantees of future performance and are subject to certain risks, uncertainties and assumptions that are difficult to predict. Therefore, our actual results could differ materially and adversely from those expressed in any forward-looking statements as a result of various factors.

Important factors that may cause such a difference include, but are not limited to, general economic and political conditions and specific conditions in the markets we address, particularly as it might effect the status of our contract manufacturing sources; the timing and successful completion of technology and product development through volume production; the rate at which our present and future customers adopt our BGA technologies and products; our ability to raise additional capital; our ability to negotiate appropriate strategic relationships; our ability to control costs and expenses; the potential unforeseen impact of product offerings from competitors; and the general economic slowdown in the technology sector and semiconductor industry. Further information on Irvine Sensors Corporation, including additional risk factors that may affect our forward looking statements, is contained in our Annual Report on Form 10-K, our Quarterly Reports on Form 10-Q, our Current Reports on Form 8-K and our other SEC filings that are available through the SEC's website (www.sec.gov).

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